AT04400R

40V N-Channel MOSFET

Features

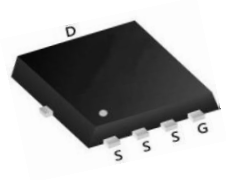
- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summary

V_{DS}	40	V
I_D	40	A
$R_{DS(ON)}$ (at V_{GS}=10V)	6.5	mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	9	mΩ

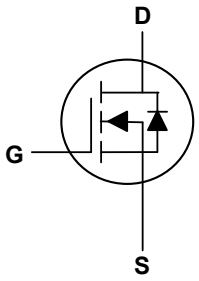
Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



DFN3X3-8L Top View

Top View



Absolute Maximum Ratings(T_C=25℃, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current, VGS @ 10V[1]	I_D@T_C=25℃	40	A
Continuous Drain Current, VGS @ 10V[1]	I_D@T_C=100℃	31	A
Pulsed Drain Current[2]	I_{DM}	140	A
Single Pulse Avalanche Energy[3]	EAS	101	mJ
Avalanche Current	I_{AS}	45	A
Total Power Dissipation[4]	P_D@T_C=25℃	36.7	W
Storage Temperature Range	T_{STG}	-55 to 150	℃
Operating Junction Temperature Range	T_J	-55 to 150	℃

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient[1]	$R_{\theta JA}$	---	75	℃/W
Thermal Resistance Junction-Case[1]	$R_{\theta JC}$	---	3.4	℃/W

Electrical Characteristics (T_J=25℃, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V , I_D=250uA	40	---	---	V
Static Drain-Source On-Resistance[2]	$R_{DS(ON)}$	V_{GS}=10V , I_D=10A	---	5	6.5	mΩ
		V_{GS}=4.5V , I_D=5A	---	6.5	9	mΩ
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS} , I_D =250uA	1.0	---	2.5	V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=32V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=55℃	---	---	5	
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
Forward Transconductance	gfs	V_{DS}=5V , I_D=5A	---	27	---	S
Total Gate Charge (4.5V)	Q_g	V_{DS}=20V , V_{GS}=4.5V , I_D=10A	---	20	---	nC
Gate-Source Charge	Q_{gs}		---	5.8	---	
Gate-Drain Charge	Q_{gd}		---	9.5	---	
Turn-On Delay Time	$T_{d(on)}$	V_{DD}=15V , V_{GS}=10V , R_G=3.3Ω, I_D=1A	---	15.2	---	ns
Rise Time	T_r		---	8.8	---	
Turn-Off Delay Time	$T_{d(off)}$		---	74	---	
Fall Time	T_f		---	7	---	
Input Capacitance	C_{iss}	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	2354	---	pF
Output Capacitance	C_{oss}		---	215	---	
Reverse Transfer Capacitance	C_{rss}		---	175	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current[1,5]	I_S	V_G=V_D=0V , Force Current	---	---	40	A
Diode Forward Voltage[2]	V_{SD}	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note:

1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=45A

4.The power dissipation is limited by 150℃ junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

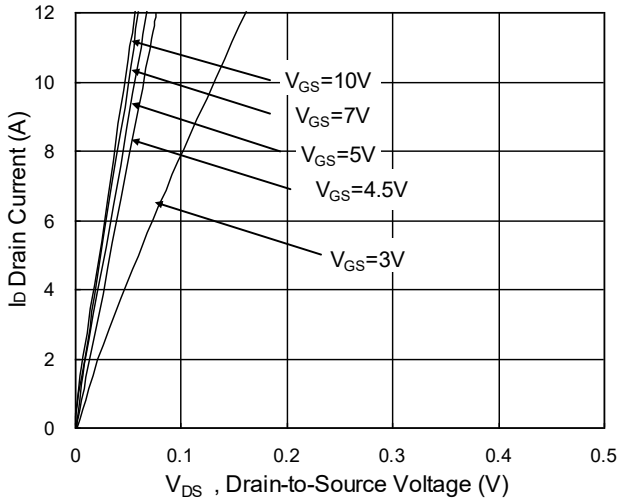


Fig.1 Typical Output Characteristics

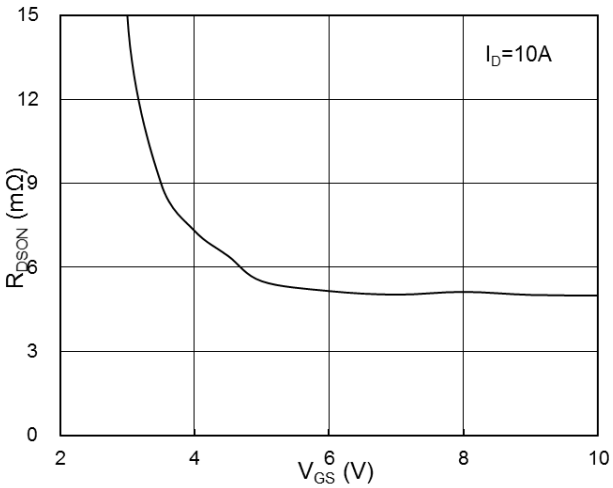


Fig.2 On-Resistance vs. G-S Voltage

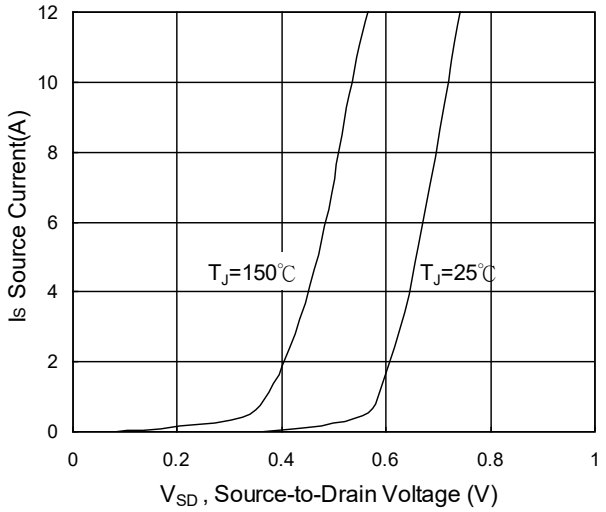


Fig.3 Source Drain Forward Characteristics

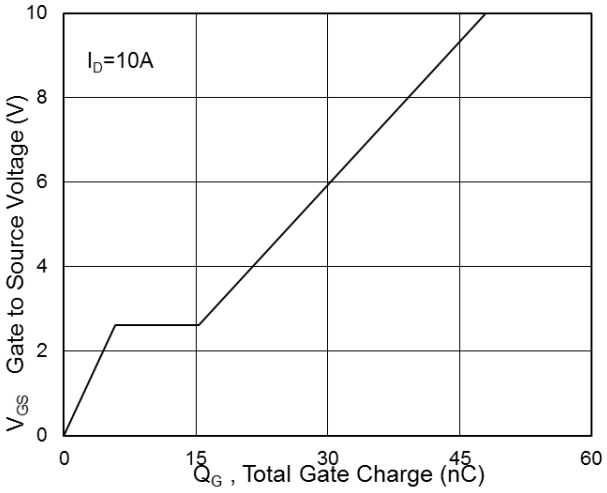


Fig.4 Gate-Charge Characteristics

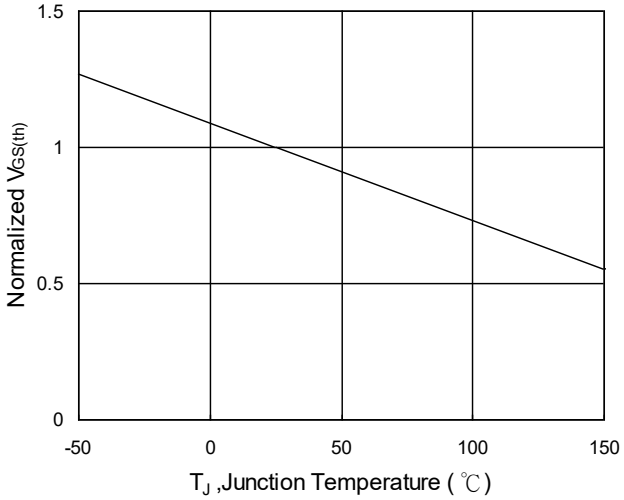


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

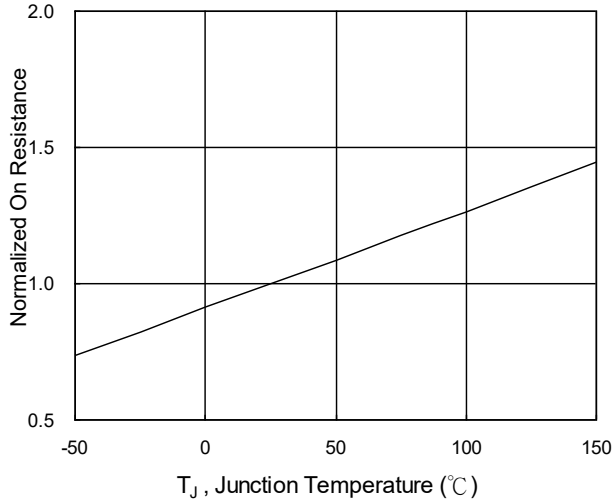


Fig.6 Normalized R_{DSON} vs. T_J

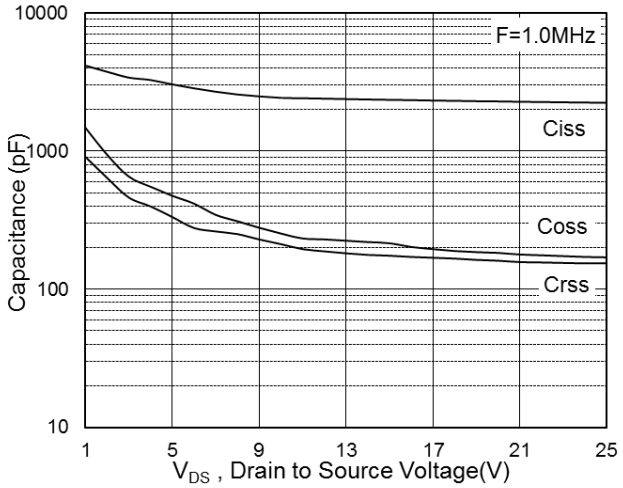


Fig.7 Capacitance

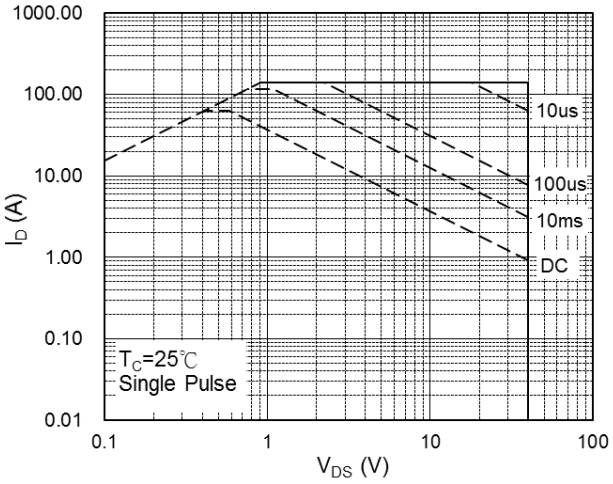


Fig.8 Safe Operating Area

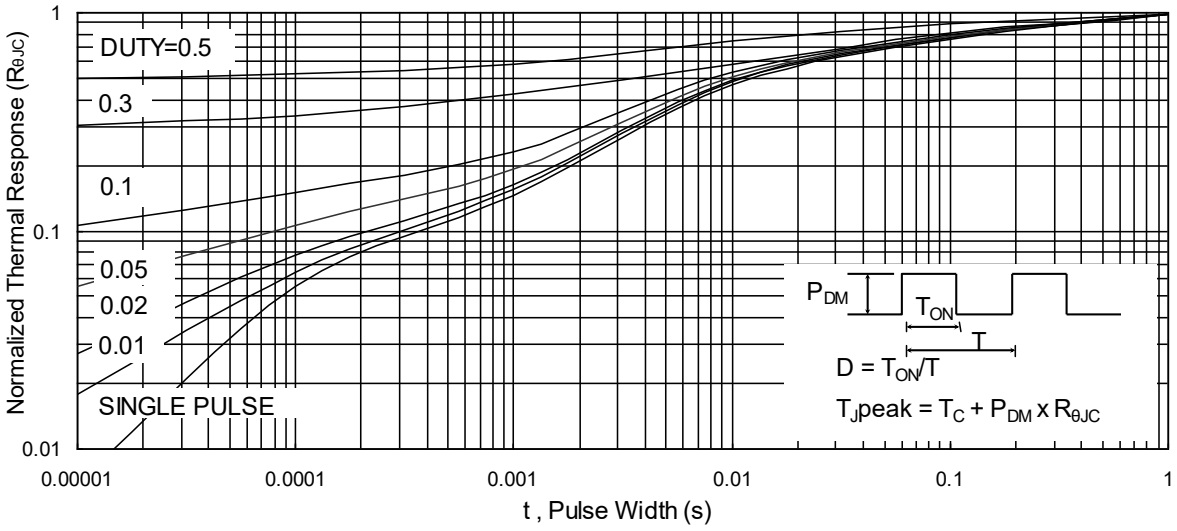


Fig.9 Normalized Maximum Transient Thermal Impedance

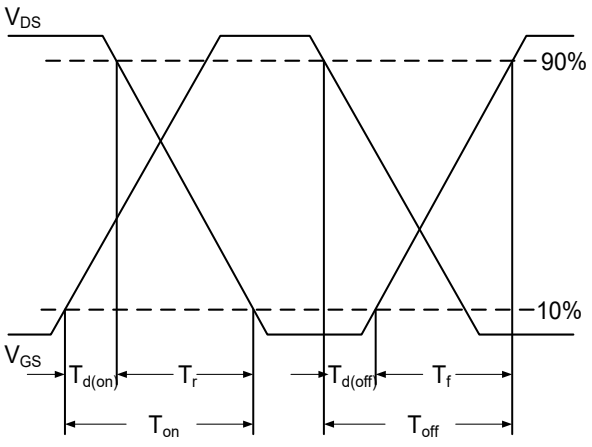


Fig.10 Switching Time Waveform

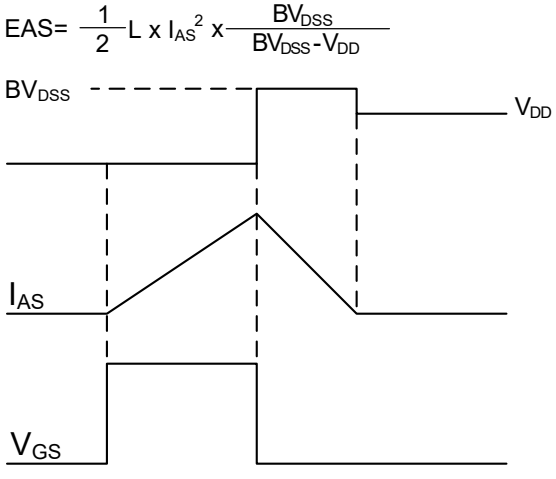
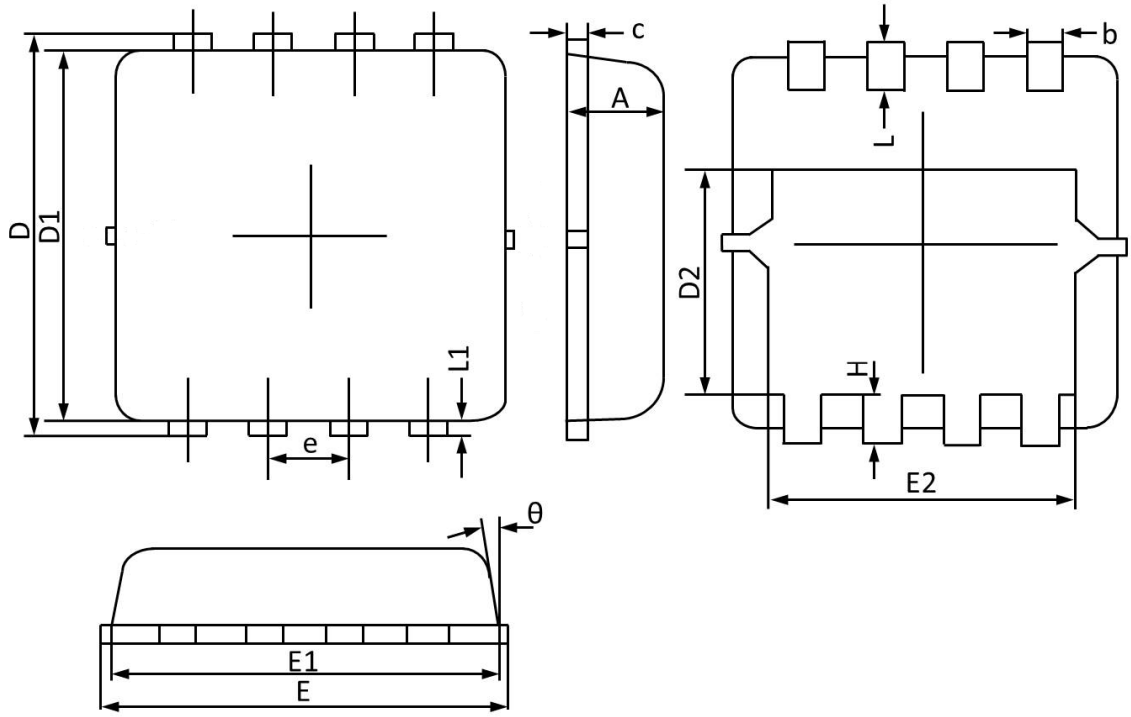


Fig.11 Unclamped Inductive Switching Wave

DFN3X3-8L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.70	0.75	0.85	**E1**	2.90	3.10	3.25
b	0.24	0.30	0.35	**E2**	2.35	2.50	2.60
c	0.10	0.17	0.25	**e**	0.65 BSC		
D	3.10	3.30	3.45	**H**	0.30	0.40	0.50
D1	2.90	3.05	3.20	**L**	0.30	0.40	0.50
D2	1.45	1.70	1.95	**L1**	--	0.13	--
E	3.05	3.25	3.40	**θ**	0°		14°